FAIRCHILD SEMICONDUCTOR®

IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information

Company Name * **Fairchild Semiconductor**	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	**Response Date*** **Sat, Aug 09, 2014 03:20 AM**
Contact Name * **David Lancaster**	Title - Contact Product Ecology	**Phone - Contact *** **801-562-7455**	**Email - Contact *** **david.lancaster@fairchildsemi.com**
Authorized Representative * **David Lancaster**	Title - Representative Product Ecology	**Phone - Representative *** **801-562-7455**	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	**Weight***	UOM	Unit Type
GBPC2506W	GBPC2506W	GBPC-W			SUBCONTRACTOR	**17.003347**	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Other	CU Alloy	Not Applicable	C	seconds	Not Applicable

* Required Field

RoHS Material Composition Declaration	**Declaration Type * Custom**

RoHS Directive 2011/65/EU	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration *	**4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions**	**Supplier Acceptance * Accepted**

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

7(a)-Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).

Declaration Signature

Supplier Signature	David Lancaster DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name GBPC-W

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Casing	Other Organic Materials	7420.000	Supplier		Epoxy Resin	7420.000	29690-82-2	436385
Chip	Other inorganic materials	27.200	Supplier		Silicon	27.200	7440-21-3	1600
Encapsulation	Thermoplastics	7475.700	B	Antimony/Antimony Compounds	Antimony Trioxide	86.700	1309-64-4	5099
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	137.000	6386-73-8	8057
			Supplier		Carbon Black	62.000	1333-86-4	3646
			Supplier		Cycloaliphatic Anhydride	1270.000	19438-60-9	74691
			Supplier		Epoxy Resin	1800.000	29690-82-2	105862
			Supplier		Silica, vitreous	4120.000	60676-86-0	242305
Ink	Other Organic Materials	4.200	Supplier		2-Propenoic acid polymer	2.940	53192-18-0	173
			Supplier		Aluminum	0.630	7429-90-5	37
			Supplier		Padimate	0.420	21245-01-2	25
			Supplier		Silica	0.105	112945-52-5	6
			Supplier		additive	0.105	947-19-3	6
Slug	Copper & its alloys	1160.000	Supplier		Copper	1160.000	7440-50-8	68222
Solder Paste	Other Nonferrous metals & alloys	20.000	A	Lead/Lead Compounds	Lead	18.500	7439-92-1	1088
			Supplier		Silver	0.500	7440-22-4	29
			Supplier		Tin	1.000	7440-31-5	59
Solder Wafer	Other Nonferrous metals & alloys	49.400	A	Lead/Lead Compounds	Lead	45.700	7439-92-1	2688
			Supplier		Silver	1.230	7440-22-4	72
			Supplier		Tin	2.470	7440-31-5	145
Wire Bond	Copper & its alloys	846.847	Supplier		Copper	846.000	7440-50-8	49755
			Supplier		Silver	0.847	7440-22-4	50